

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1107	NABETA.IN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/14 12:10
L2	37	"257"/\$.CCLS. AND 1	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:11
L3	12	"438"/\$.CCLS. AND 1	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:12
L4	4371	257/98	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:16
L5	578	257/E21.002	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:18
L6	8	257/E31.129	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:18
L7	3601	257/99	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:19
L8	1908	257/100	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:19

L9	3297	257/79	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:21
L10	981	BLUE ADJ LED SAME DEVICE AND "257"/\$.CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:22
L11	173	TRANSPARENT SAME INORGANIC AND PHOSPHOR AND VAPOR ADJ PHASE	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:23
L12	36	(AEROSOL OR SPRAY) AND 11	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 12:26
L13	20	TRANSPARENT SAME INORGANIC AND PHOSPHOR AND VAPOR ADJ PHASE AND DIODE.CLM.	US-PGPUB	OR	ON	2009/05/14 12:33
L14	2269	(438/22).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/14 12:34
L15	384	(438/25).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/14 12:35
L16	799	(438/26).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/14 12:37
L17	550	(438/27).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/14 12:37

S1	1	"20020181725"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/13 13:32
S2	0	(semiconductor adj substrate and backer adj etch and (conductor adj layer or path))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 13:34
S3	0	(semiconductor adj substrate and backed adj etch and (conductor adj layer or conductor adj path))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 13:35
S4	0	(semiconductor adj substrate and backed adj etch and conductor adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 13:35
S5	15	(semiconductor adj substrate and backed and etch and conductor adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 13:36
S6	587	(381/174).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/13 13:38
S7	2	conductor and substrate and backed adj etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/13 14:08
S8	19	substrate and backed adj etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 14:09
S9	935	(381/191).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2009/05/13 14:17

S10	9813	"381" and etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 14:56
S11	0	memberance and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 14:57
S12	2857	conductor and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/13 14:57
S13	6	"5866800"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 09:52
S14	37	"5237867"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 10:45
S15	2	"7466834"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 10:54
S16	1	"20020181725"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2009/05/14 10:57

5/14/09 1:15:12 PM

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